

**PATENT ASSIGNMENT**

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
James A. Baron	06/02/2008
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	Seicon Limited
<b>Street Address:</b>	1936 Andover Road
<b>City:</b>	Columbus
<b>State/Country:</b>	OHIO
<b>Postal Code:</b>	43212
<b>PROPERTY NUMBERS Total: 2</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	60906668
Application Number:	12077065
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	3078300-087714
<b>NAME OF SUBMITTER:</b>	Richard M. Mescher
<b>Total Attachments: 2</b> source=assign#page1.tif source=assign#page2.tif	

CH \$80.00 60906668

## ASSIGNMENT

Whereas, I, **James A. Baron** have solely invented certain new and useful improvements in a “**Platform Isolator**”, for which we filed a United States patent application numbers 60/906,668 and 12/077,065 (Porter, Wright, Morris & Arthur Docket No. 3078300-087714PI);

And whereas, **Seicon Limited**, having a mailing address of 1936 Andover Road, Columbus, Ohio 43212, is desirous of acquiring the entire right, title and interest in, to and under said invention and said patent applications, any continuing applications, continuations-in-part, divisional applications, refiled or reissue applications made in the United States of America and all other Nations which may result from said invention and information disclosed in said applications, and any and all Letters Patent of the United States and other Nations which may be issued therefrom;

Now, therefore, in accordance with my employment agreement and for other good and valuable consideration, the receipt of which is hereby acknowledged, I, **James A. Baron** do hereby sell, assign and transfer to **Seicon Limited** the entire and undivided right, title and interest in and to my invention of new and useful improvements in and to a “**Platform Isolator**”, said applications for letters patent, the invention therein described, and all rights appurtenant thereto and in all our applications related thereto, including each of the following: the right to apply for any letters patent for said invention in the United States of America and in any and all foreign countries, any and all other applications for letters patent on said invention, in whatsoever countries, including all divisional, renewal, substitute and continuation applications based in whole or in part upon said invention or upon said application or related thereto; any and all letters patent that may issue thereon in the United States and foreign countries and any and all reissues, extensions, renewals, divisions, or continuations of letters patent granted for said inventions or upon said applications, to the full end of the term or terms for which said letters patent may be issued; and every priority or other right accorded by every international convention, treaty or agreement that is or may be predicated upon or arise from said invention, application and other applications or letters patent therefor, all to be held by **Seicon Limited**, and its successors and assigns, all the same as I would have held and enjoyed had this Assignment not been made.

I hereby authorize and grant the right to **Seicon Limited** to file and prosecute patent applications in any or all countries on all or any part of said invention in my name or in the name of **Seicon Limited** or otherwise, as **Seicon Limited** may deem advisable under any international convention, treaty, or agreement or otherwise.

I hereby request and authorize the Commissioner of Patents and Trademarks of the United States and the empowered officials of all other countries to grant, issue and transfer any letters patent for said invention to **Seicon Limited**, as assignee of the entire right, title and interest therein, in accordance with this instrument of assignment.

I hereby represent and warrant that there are no outstanding rights or interest inconsistent with the rights and interests granted herein; I covenant that I will not execute, grant, or transfer any rights or interests inconsistent herewith, I bind myself, my heirs, executors, administrators and legal representatives to execute and deliver to **Seicon Limited**, and its successors and assigns, any further documents or instruments and to perform any and all further acts that may be deemed necessary to enable it, and its successors and assigns, to file applications for letters patent for said invention in any country in which it may elect to file such applications, and to vest in **Seicon Limited**, and its successors and assigns, the title herein conveyed and intended to so be, and to enable such title to be recorded in the United States and each foreign country in which each such application may be filed so that any patent issued thereon shall be issued to vest in **Seicon Limited**, and its successors and assigns; and I further covenant and agree, for myself and my executors, administrators and legal representatives, that I and they will, upon request, communicate to **Seicon Limited**, and its successors and assigns, any facts relating to said invention and the history thereof, known to me or them and that I and they will testify as to the same in any proceeding, interference or litigation when requested to do so by to **Seicon Limited**, and its successors and assigns.

Inventor:

**James A. Baron**

Inventor's Signature:

Date Signed:

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